

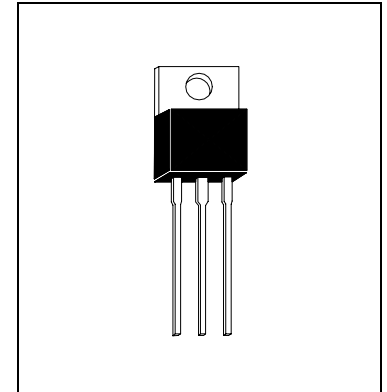


# HMJE3055T

NPN EPITAXIAL PLANAR TRANSISTOR

## Description

The HMJE3055T is designed for general purpose of amplifier and switching applications.



## Absolute Maximum Ratings (Ta=25°C)

- Maximum Temperature  
 Storage Temperature ..... -55 ~ +150 °C  
 Junction Temperature ..... 150 °C Maximum
- Maximum Power Dissipation  
 Total Power Dissipation (Tc=25°C) ..... 75 W  
 Total Power Dissipation (Ta=25°C) ..... 0.6 W
- Maximum Voltages and Currents (Ta=25°C)  
 BVCBO Collector to Base Voltage ..... 70 V  
 BVCEO Collector to Emitter Voltage ..... 60 V  
 BVEBO Emitter to Base Voltage ..... 5 V  
 IC Collector Current ..... 10 A  
 IB Base Current ..... 6 A

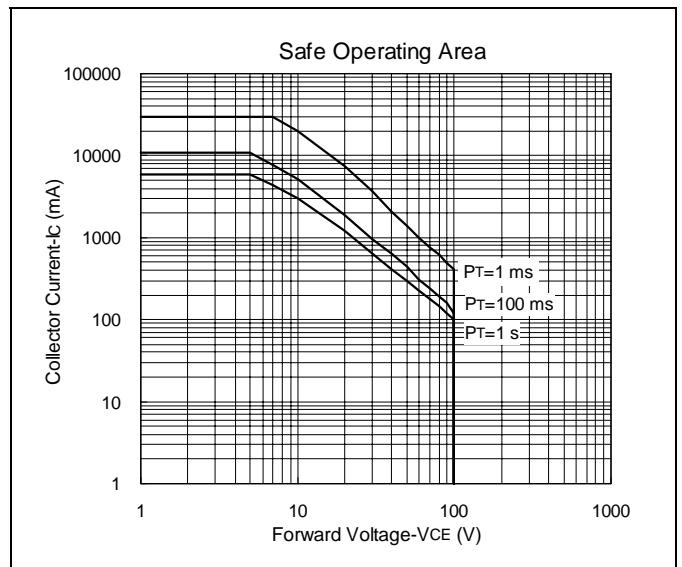
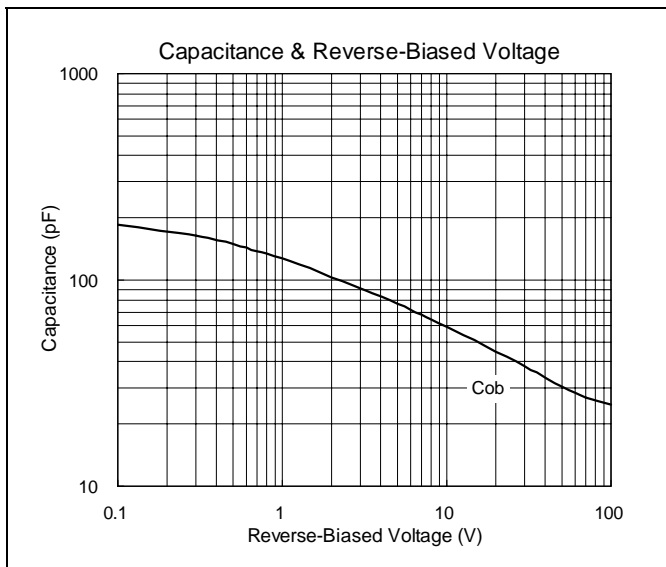
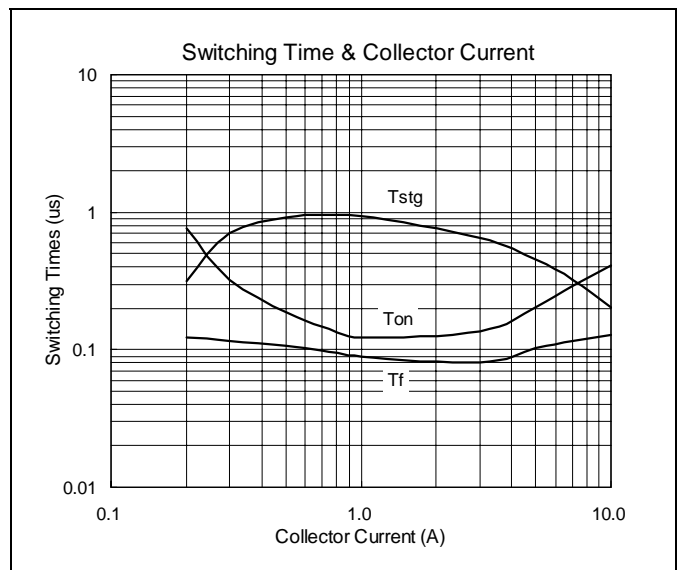
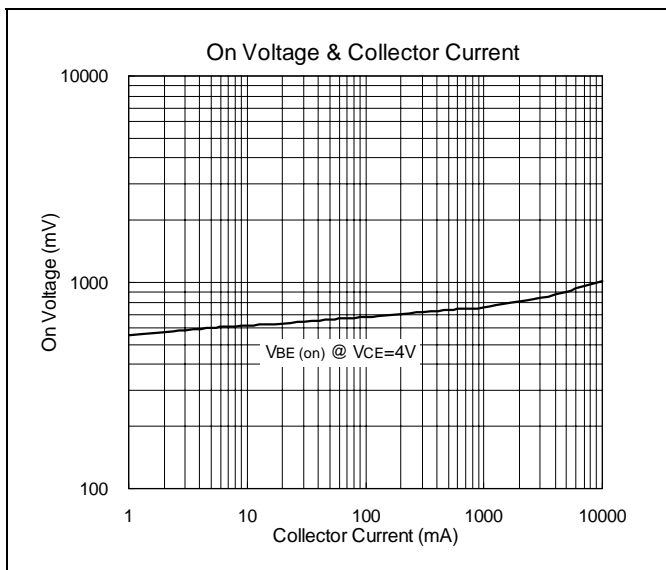
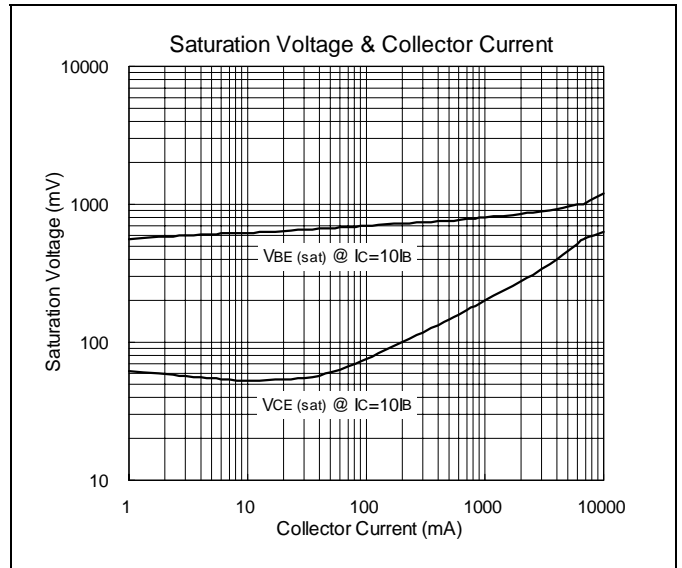
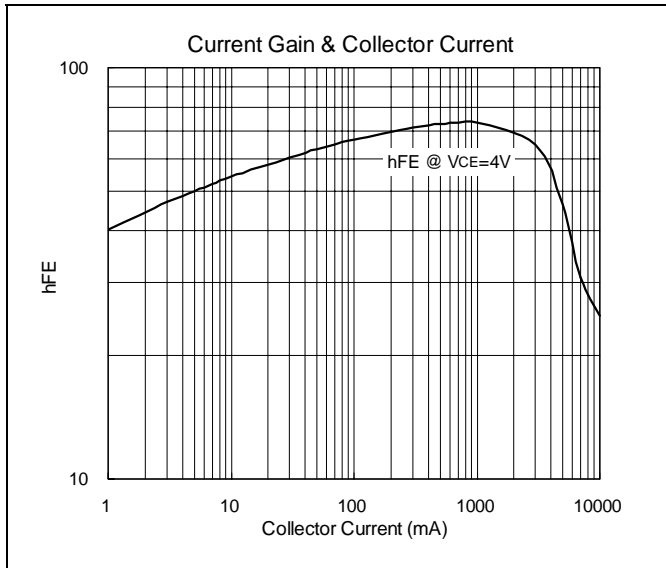
## Characteristics (Ta=25°C)

Symbol	Min.	Typ.	Max.	Unit	Test Conditions
BVCEO	60	-	-	V	IC=200mA, IB=0
BVCBO	70	-	-	V	IC=10mA, IE=0
BVEBO	5	-	-	V	IE=10mA, IC=0
ICBO	-	-	1.	mA	VCB=70V, IE=0
ICEX	-	-	1.	mA	VCE=70V, VEB(off)=1.5V
ICEO	-	-	700	uA	VCE=30V, IB=0
IEBO	-	-	5	mA	VEB=5V, IC=0
*VCE(sat)1	-	-	1.1	V	IC=4A, IB=400mA
*VCE(sat)2	-	-	8.0	V	IC=10A, IB=3.3A
*VBE(on)	-	-	1.8	V	IC=4A, VCE=4V
*hFE1	20	-	100		IC=4A, VCE=4V
*hFE2	5	-	-		IC=10A, VCE=4V
fT	2	-	-	MHz	VCE=10V, IC=500mA, f=0.5MHz

\*Pulse Test : Pulse Width ≤380us, Duty Cycle≤2%

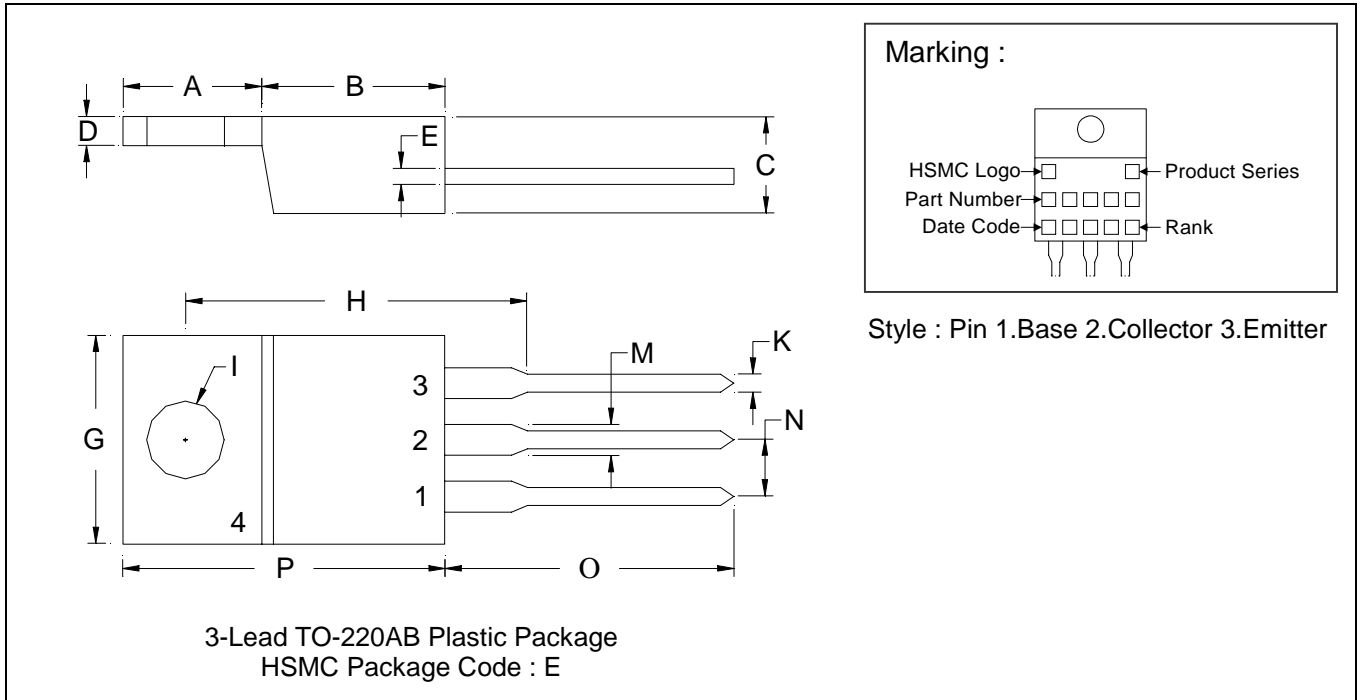


### Characteristics Curve





### TO-220AB Dimension



\*:Typical

DIM	Inches		Millimeters		DIM	Inches		Millimeters	
	Min.	Max.	Min.	Max.		Min.	Max.	Min.	Max.
A	0.2197	0.2949	5.58	7.49	I	-	*0.1508	-	*3.83
B	0.3299	0.3504	8.38	8.90	K	0.0295	0.0374	0.75	0.95
C	0.1732	0.185	4.40	4.70	M	0.0449	0.0551	1.14	1.40
D	0.0453	0.0547	1.15	1.39	N	-	*0.1000	-	*2.54
E	0.0138	0.0236	0.35	0.60	O	0.5000	0.5618	12.70	14.27
G	0.3803	0.4047	9.66	10.28	P	0.5701	0.6248	14.48	15.87
H	-	*0.6398	-	*16.25					

- Notes : 1.Dimension and tolerance based on our Spec. dated Sep. 07,1997.  
 2.Controlling dimension : millimeters.  
 3.Maximum lead thickness includes lead finish thickness, and minimum lead thickness is the minimum thickness of base material.  
 4.If there is any question with packing specification or packing method, please contact your local HSMC sales office.

**Material :**

- Lead : 42 Alloy ; solder plating
- Mold Compound : Epoxy resin family, flammability solid burning class:UL94V-0

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